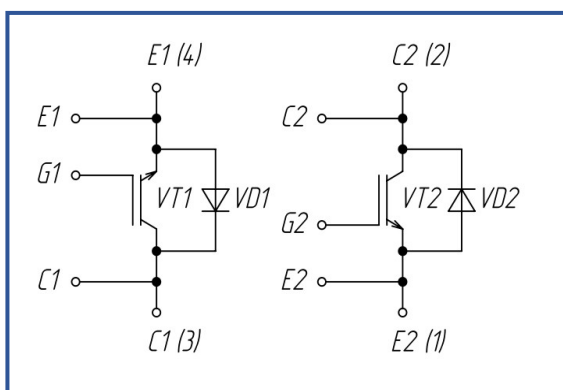
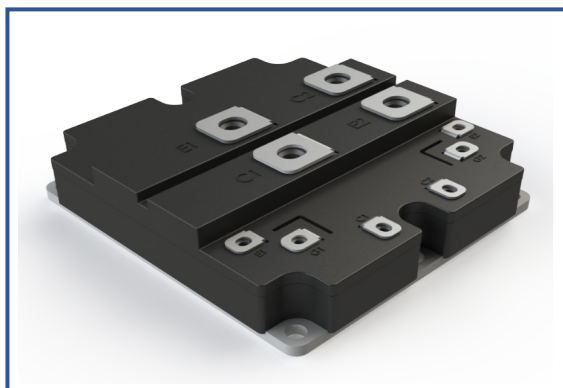


IGBT high-power module
1700 V 1200 A

Chip features

- IGBT chip
 - low $V_{CE(sat)}$ value
 - 10 μs short circuit of 150°C
 - square RBSOA of 2xIC
 - low EMI
- FRD chip
 - fast and soft reverse recovery
 - low voltage drop

Design features

- AlSiC baseplate
- AlN DBC substrate
- ultrasonically welded power terminals

Typical application

- AC and DC motor drives
- high-power converters
- wind-powered generator inverters
- industrial equipment

Maximum rated values

Definition	Symbol	Conditions	Value	Unit
IGBT				
Collector-Emitter voltage	V_{CES}	$V_{GE} = 0$.	1700	V
Maximum allowable collector current (continuous)	$I_{C\ 25}$	$T_{vj\ (max)} = 175^{\circ}C$; $T_c = 25^{\circ}C$.	1698	A
	$I_{C\ 80}$	$T_{vj\ (max)} = 175^{\circ}C$; $T_c = 80^{\circ}C$.	1200	A
Repetitive peak collector current ^{*1}	I_{CRM}	$I_{CRM} = 2 \times I_{C\ nom}$; $t_p = 1\ ms$.	2400	A
Short-circuit duration	t_{psc}	$T_{vj} = 25^{\circ}C$; $V_{GE} = \pm 15\ V$; $V_{CE} = 1000\ V$; $R_{G\ on} = 1\ \Omega$; $R_{G\ off} = 20\ \Omega$.	10	μs
		$T_{vj} = 150^{\circ}C$; $V_{GE} = \pm 15\ V$; $V_{CE} = 1000\ V$; $R_{G\ on} = 1\ \Omega$; $R_{G\ off} = 20\ \Omega$.	10	
Gate-Emitter voltage	V_{GES}		± 20	V
Junction operating temperature	$T_{vj\ (op)}$		-40...+150	°C
Inverse diode \ Freewheeling diode				
Repetitive peak reverse voltage	V_{RRM}	$V_{GE} = 0\ V$.	1700	V
Maximum allowable forward current (continuous)	$I_{F\ 25}$	$T_{vj\ (max)} = 175^{\circ}C$; $T_c = 25^{\circ}C$.	1338	A
	$I_{F\ 80}$	$T_{vj\ (max)} = 175^{\circ}C$; $T_c = 80^{\circ}C$.	1001	A
Repetitive peak forward current ^{*1}	I_{FRM}	$I_{FRM} = 2 \times I_{F\ nom}$; $t_p = 1\ ms$.	2400	A
Junction operating temperature	$T_{vj\ (op)}$		-40...+150	°C
Module				
Storage temperature	T_{stg}		-55...+50	°C
Isolation voltage	V_{isol}	AC sin 50 Hz; $t = 1\ min$.	6000	V

^{*1} Pulse width and repetition rate should be such that device junction temperature does not exceed maximum T_{vj} rating.



Characteristics

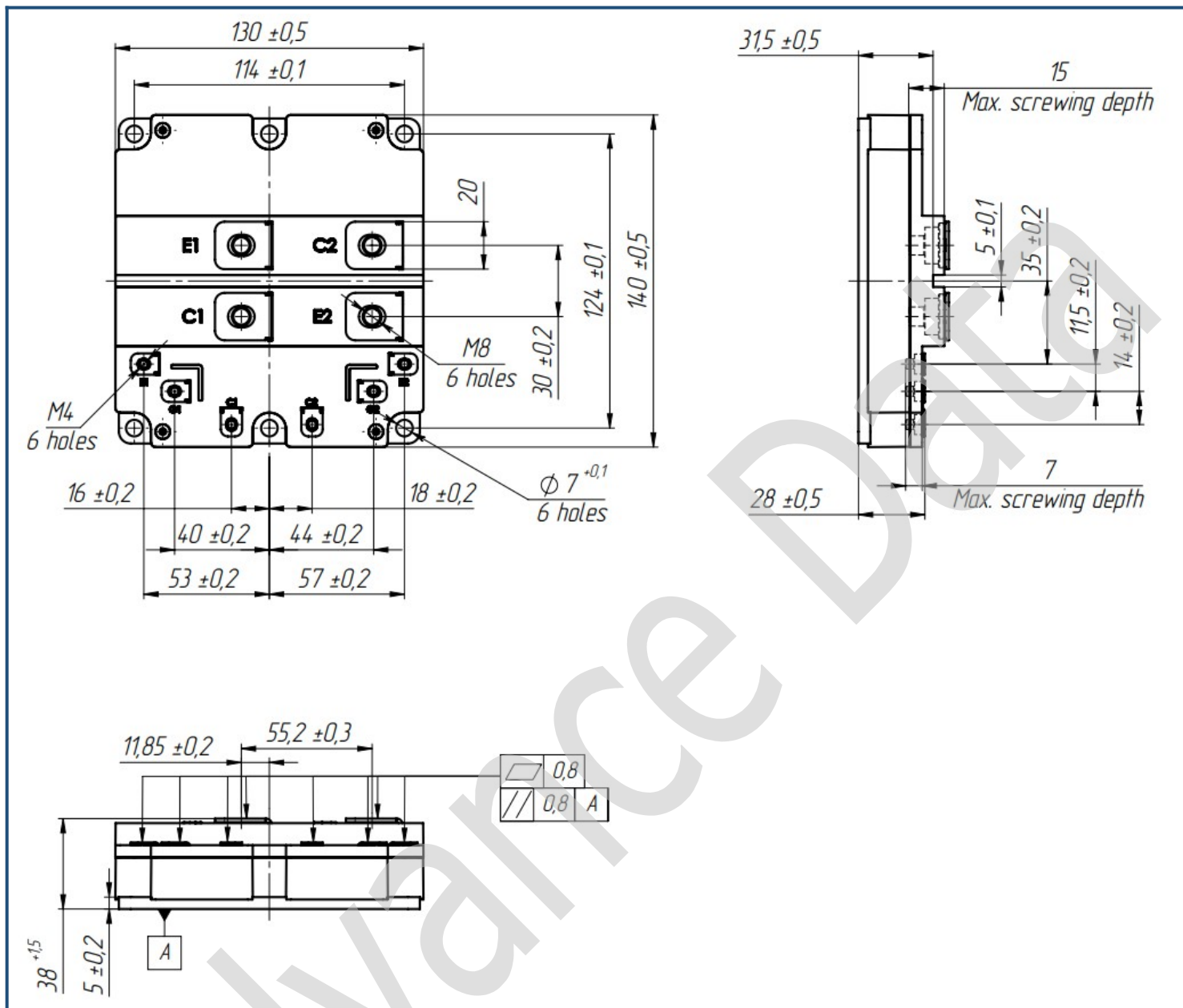
Definition	Symbol	Conditions		Value			Unit.
				min.	typ.	max.	
IGBT							
Collector-Emitter saturation voltage	V _{CEsat}	V _{GE} = +15 V; I _C = 1200 A; t _u = 1 ms.	T _{vj} = 25°C	-	2.15	-	V
			T _{vj} = 150°C	-	2.70	-	V
Gate-Emitter threshold voltage	V _{GE(th)}	I _C = 48 mA; U _{CE} = U _{GE} ; T _{vj} = 25°C; t _u = 2 ms.		5.70	5.90	6.10	V
Collector-Emitter cut-off current	I _{CES}	V _{CE} = 1700 V; t _u = 10 ms; V _{GE} = 0.	T _{vj} = 25°C	-	-	0.40	mA
			T _{vj} = 150°C	-	-	7.00	mA
Gate-Emitter leakage current	I _{GES}	V _{CE} = 0; V _{GE} = ±20 V; T _{vj} = 25°C; t _u = const.		-	-	500	nA
Input capacitance	C _{ies}	V _{CE} = 25 V; V _{GE} = 0 V; f = 1 MHz; T _{vj} = 25°C.		-	465.6	-	nF
Output capacitance	C _{oes}			-	19.52	-	nF
Reverse transfer capacitance	C _{res}			-	2.88	-	nF
Total gate charge	Q _G	V _{GE} = -15...+15 V.		-	7.50	-	μC
Internal gate resistance	R _{Gint}	T _{vj} = 25°C.		-	0.93	-	Ω
Turn-on delay time	t _{d(on)}	V _{CE} = 920 V; V _{GE} = ±15 V; I _{C max} = 1200 A; R _G = 5 Ω.	T _{vj} = 25°C	-	740	-	ns
			T _{vj} = 150°C	-	720	-	
Rise time	t _{ri}		T _{vj} = 25°C	-	520	-	ns
			T _{vj} = 150°C	-	570	-	
Turn-on energy	E _{on}		T _{vj} = 25°C	-	970	-	mJ
			T _{vj} = 150°C	-	1180	-	
Turn-off delay time	t _{d(off)}		T _{vj} = 25°C	-	1760	-	ns
			T _{vj} = 150°C	-	1870	-	
Fall time	t _{fi}		T _{vj} = 25°C	-	400	-	ns
			T _{vj} = 150°C	-	500	-	
Turn-off energy	E _{off}		T _{vj} = 25°C	-	480	-	mJ
			T _{vj} = 150°C	-	520	-	
Collector-emitter threshold voltage	V _{CE0}	V _{GE} = +15 V; T _{vj} = 150°C;		-	-	0.85	V
On-State slope resistance (IGBT)	r _{CE0}	I _{CE1} = 300 A; I _{CE2} = 1200 A; t _u = 1 ms		-	-	1.50	mΩ
Thermal resistance junction to case	R _{th(j-c)}	DC; V _{GE} = +15 V.		-	-	0.026	K/W
Inverse diode \ Freewheeling diode							
Forward voltage drop	V _F	I _F = 1200 A; V _{GE} = 0; t _u = 1 ms.	T _{vj} = 25°C	-	2.00	-	V
			T _{vj} = 150°C	-	2.10	-	V
Reverse recovery time	t _{rr}	V _{CE} = 920 V; V _{GE} = ±15 V; I _{C max} = 1200 A; R _G = 5 Ω.	T _{vj} = 25°C	-	870	-	ns
			T _{vj} = 150°C	-	1330	-	ns
Peak reverse current	I _{RM}		T _{vj} = 25°C	-	480	-	A
			T _{vj} = 150°C	-	530	-	A
Recovered charge	Q _r		T _{vj} = 25°C	-	210	-	μC
			T _{vj} = 150°C	-	350	-	μC
Reverse recovery energy	E _{rec}		T _{vj} = 25°C	-	100	-	mJ
			T _{vj} = 150°C	-	180	-	mJ
Threshold voltage	V _(T0)	T _{vj} = 150°C; V _{GE} = 0; I _{F1} = 300 A;		-	-	0.87	V
Forward slope resistance	r _T	I _{F2} = 1200 A; t _u = 1 ms		-	-	1.02	mΩ
Thermal resistance junction to case	R _{th(JC-D)}	DC; U _{GE} = +15 V.		-	-	0.050	K/W

Module							
Pin resistance	R_{Pxy}	$T_{vj} = 25^{\circ}\text{C}$	$R_{P4-3/1-2}$	-	0.31	-	mΩ
Parasitic inductance between terminals	L_{Pxy}		$L_{P4-3/1-2}$	-	28.60	-	nH
Thermal resistance case to heatsink	R_{thCH}	per module		-	6.00	-	K/kW
Mounting torque for screws to heatsink	M_s	to heatsink M6		-	5.00	-	N*m
Mounting torque for screws to control terminal	M_t	to terminals M4		-	2.00	-	N*m
Mounting torque for screws to power terminal	M_t	to terminals M8		-	9.00	-	N*m
Creepage distance	d_s			15.00	-	-	mm
Clearance	d_a			10.00	-	-	mm
Comparative Tracking Index	CTI			600	-	-	
Weight	W			-	-	900	g

“ - “ Data will be refined as additional tests are conducted and statistics are collected.

Notes:

- Insulating material operating temperature 125°C max;
- Case temperature 125°C max;
- The recommended operating junction temperature $T_{vj\text{ op}} = -40 \div +150^{\circ}\text{C}$.

Overall dimensions: Package type – SM

Part numbering guide

MISM	-	DS	17	SM	-	1200	N	
MISM								IGBT module package type: SM
		DS						Double switch
			17					Voltage rating ($V_{CES}/100$)
				SM				IGBT+FRD chipset modification
						1200		Current Rating
							N	Climatic version: normal climate

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